

SUBMINIATURE SOLID STATE LAMP

Part Number: AM2520EC09 High Efficiency Red

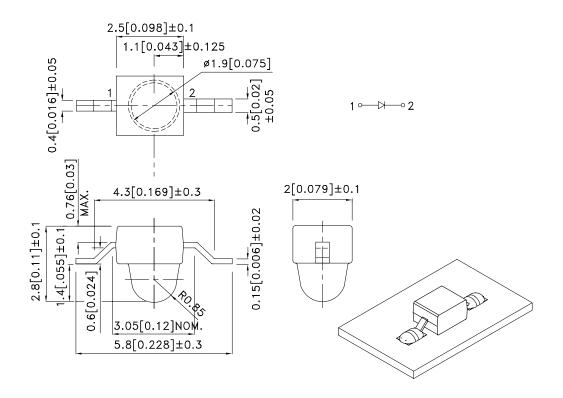
Features

- SUBMINIA TURE PACKAGE.
- WIDE VIEWING ANGLE.
- Z-BEND LEAD.
- LONG LIFE SOLID STATE RELIABILITY.
- LOW PACKAGE PROFILE.
- MOISTURE SENSITIVITY LEVEL: LEVEL 3.
- PACKAGE: 1000PCS / REEL.
- RoHS COMPLIANT.

Description

The High Efficiency Red source color devices are made with Gallium Arsenide Phosphide on Gallium Phosphide Orange Light Emitting Diode.

Package Dimensions



Notes:

- All dimensions are in millimeters (inches).
 Tolerance is ±0.25(0.01") unless otherwise noted.
- 3. Lead spacing is measured where the leads emerge from the package.
- 4. Specifications are subject to change without notice.
- 5. The device has a single mounting surface. The device must be mounted according to the specifications.



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Selection Guide

Part No.	Dice	Lens Type	lv (mcd) [2] @ 20mA		Viewing Angle [1]
			Min.	Тур.	2θ1/2
AM2520EC09	High Efficiency Red (GaAsP/GaP)	WATER CLEAR	10	70	20°

- 1. θ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value. 2. Luminous intensity/ luminous Flux: +/-15%.

Electrical / Optical Characteristics at TA=25°C

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Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	High Efficiency Red	627		nm	IF=20mA
λD [1]	Dominant Wavelength	High Efficiency Red	625		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	High Efficiency Red	45		nm	IF=20mA
С	Capacitance	High Efficiency Red	15		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	High Efficiency Red	2	2.5	V	IF=20mA
lr	Reverse Current	High Efficiency Red		10	uA	V _R =5V

1.Wavelength: +/-1nm. 2. Forward Voltage: +/-0.1V.

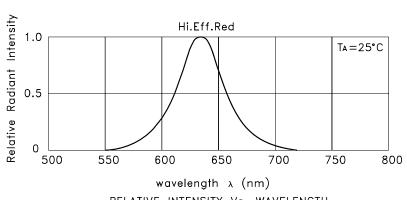
Absolute Maximum Ratings at TA=25°C

Parameter	High Efficiency Red					
Power dissipation	75	mW				
DC Forward Current	30	mA				
Peak Forward Current [1]	160	mA				
Reverse Voltage	5	V				
Operating Temperature	-40°C To +85°C					
Storage Temperature	-40°C To +85°C					

Note:

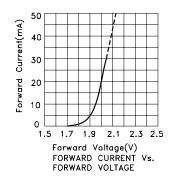
1. 1/10 Duty Cycle, 0.1ms Pulse Width.

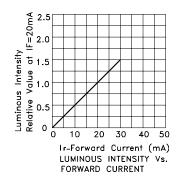
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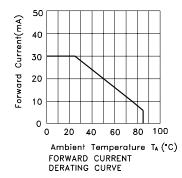


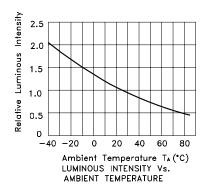
RELATIVE INTENSITY Vs. WAVELENGTH

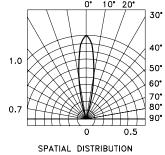
High Efficiency Red AM2520EC09







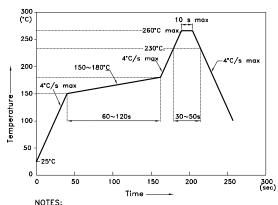




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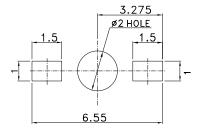
Reflow Soldering Profile For Lead-free SMT Process.



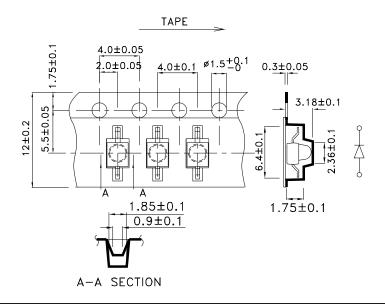
- NOTES:

 1.We recommend the reflow temperature 245°C(+/-5°C).The maximum soldering temperature should be limited to 260°C. 2.Don't cause stress to the epoxy resin while it is exposed to high temperature.
 3.Number of reflow process shall be 2 times or less.

Recommended Soldering Pattern (Units: mm; Tolerance: ± 0.1)



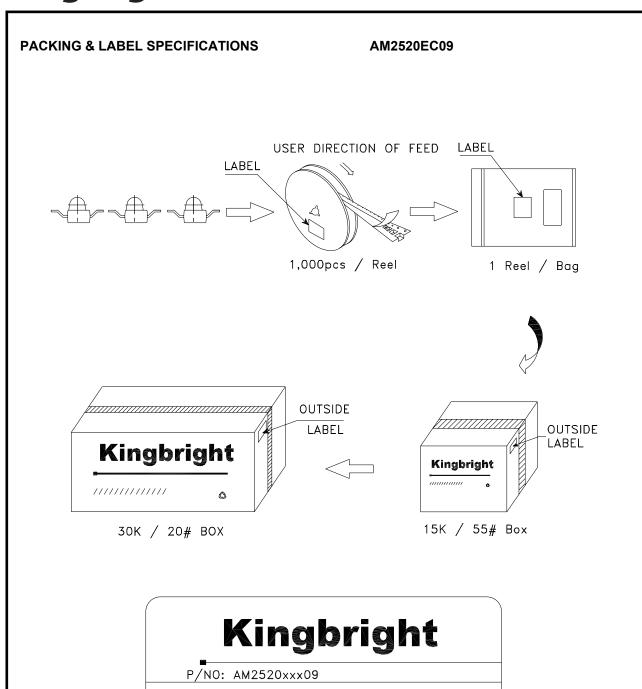
Tape Specifications (Units: mm)

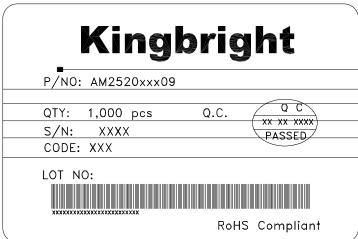


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